

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1 – 54. (Canceled)

55. (New) A circuitry component comprising:

a semiconductor device;

a metal pillar over said semiconductor device, wherein said metal pillar has a thickness of between 10 and 100 microns;

a metal layer over said metal pillar, wherein said metal layer has a bottom surface partially covered by said metal pillar and partially not covered by said metal pillar; and

a solder metal over said metal layer.

56. (New) The circuitry component of Claim 55 used to be connected to a substrate, wherein said substrate has a pad having an edge not covered by a solder mask, and wherein said solder metal is bonded to said pad.

57. (New) The chip package of Claim 55, wherein the distance between an edge of said metal layer and an edge of said metal pillar is greater than 0.2 microns.

58. (New) The chip package of Claim 55, wherein said semiconductor device comprises a pad and a passivation layer, said pad exposed by an opening in said passivation layer, wherein said metal pillar is over said pad.

59. (New) The chip package of Claim 55 further comprising a barrier between said bump and said pad.